



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN20230327005.1**  
**Qualify additional Assembly site for select SOT-23-THIN Package devices**  
**Change Notification / Sample Request**

**Date:** March 30, 2023  
**To:** TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team  
SC Business Services

**20230327005.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TLV70036DDCR	null
TPS3701DDCR	null
TPS3701DDCT	null
TPS563210ADDFT	null
TPS79915DDCR	null
TPS79915DDCT	null
TPS562219ADDFT	null
TPS565208DDCT	null
TPS79901DDCT	null
TPS79912DDCT	null
TLV70033DDCR	null
TPS3700DDCR	null
TPS3700DDCT	null
TLV70028DDCT	null
TPS562219ADDFT	null
TPS563219ADDFT	null
TPS79933DDCR	null
TPS3710DDCR	null
TPS563210ADDFT	null
TPS565208DDCR	null
TPS79901DDCR	null
REG71050DDCR	null
TPS3702CX33DDCR	null
TLV9352IDDFR	null
TPS73433DDCT	null
TLV70018DDCT	null
TLV70030DDCR	null
TLV70032DDCT	null
TLV70033DDCT	null
TLV70018DDCR	null
TLV70025DDCR	null
TPS79925DDCT	null
TLV70015DDCR	null
REG71050DDCT	null
TPS62561DDCR	null
TPS565201DDCR	null
TPS565201DDCT	null
TPS62260DDCR	null
TPS62260DDCT	null
TLV9062IDDFR	null
TPS79912DDCR	null
TPS563210DDFR	null
TPS79933DDCT	null
TPS62240DDCR	null
TPS562210ADDFT	null
TPS562210DDFR	null
TLV6703DDCR	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20230327005.1		<b>PCN Date:</b>	March 30, 2023	
<b>Title:</b>	Qualify additional Assembly site for select SOT-23-THIN Package devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	June 28, 2023		<b>Sample requests accepted until:</b>	Apr 28, 2023	
*Sample requests received after (Apr. 28, 2023) will not be supported.					
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Materials
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:					
<b>Group 1 Device:</b>					
<b>SOT-23- THIN</b>					
Assembly Sites		PHI, HNA, JCETC8, JCETJY, UTL2, TIEMA, CDAT			
Lead Finish		NiPdAu, Matte Sn			
Mount Compound		400180 400194 4207123 1120999A2 4223872 4226215			
Mold Compound		450207 450423 4222198 120800005407 8097131			
Bond wire type		Au, Cu			
Bond wire diameter		20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)			
<b>Group 2 Device:</b>					
<b>SOT-23- THIN -FC</b>					
Assembly Sites		PHI, HNA, JCETC8, JCETJY, UTL2, TIEMA, CDAT			
Lead Finish		NiPdAu, Matte Sn			
Mold Compound		450207 450423 4222198 120800005407 8097131			
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					

None

### Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

### Changes to product identification resulting from this PCN:

Assembly Site		
UTAC	Assembly Site Origin (22L)	ASO: NS2
Hana	Assembly Site Origin (22L)	ASO: HNT
TI Philippines	Assembly Site Origin (22L)	ASO: PHI
JCETJY	Assembly Site Origin (22L)	ASO: JCE
JCETJ8	Assembly Site Origin (22L)	ASO: JC8
TI Chengdu	Assembly Site Origin (22L)	ASO: CDA
TI Melaka	Assembly Site Origin (22L)	ASO: CU6

Sample product shipping label (not actual product label)

**TEXAS  
INSTRUMENTS**  
MADE IN: Malaysia  
2DC: 20:  
MSL 2 / 260C / 1 YEAR  
MSL 1 / 235C / UNLIM  
SEAL DT  
03 / 29 / 04  
OPT:  
ITEM: 39  
LBL: 5A (L)T0:1750

**G4**



(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CS0: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS

### Group 1 Product Affected:

TLV70012DDCR	TLV70032DDCT	TPS79915DDCR	TPS79933DDCT
TLV70012DDCT	TLV70033DDCR	TPS79915DDCT	TPS79942DDCR
TLV70013DDCR	TLV70033DDCT	TPS799185DDCR	TPS79942DDCT
TLV70013DDCT	TLV70036DDCR	TPS799185DDCT	REG71050DDCR
TLV70015DDCR	TLV70036DDCT	TPS79918DDCR	REG71050DDCT
TLV70015DDCT	TPS62240DDCR	TPS79918DDCT	REG71055DDCR
TLV70018DDCR	TPS62260DDCR	TPS79925DDCR	REG71055DDCT
TLV70018DDCT	TPS62260DDCT	TPS79925DDCT	TLV6703DDCR
TLV70019DDCR	TPS62561DDCR	TPS79927DDCR	TPS3700DDCR
TLV70019DDCT	TPS73401DDCR	TPS79927DDCT	TPS3700DDCR2
TLV70022DDCR	TPS73401DDCT	TPS799285DDCR	TPS3700DDCT
TLV70022DDCT	TPS73433DDCR	TPS799285DDCT	TPS3701DDCR
TLV70025DDCR	TPS73433DDCT	TPS79928DDCR	TPS3701DDCT
TLV70025DDCT	TPS79901DDCR	TPS79928DDCT	TPS3702CX33DDCR
TLV70028DDCR	TPS79901DDCT	TPS79930DDCR	TPS3710DDCR
TLV70028DDCT	TPS79912DDCR	TPS79930DDCT	TLV9062IDDFR
TLV70030DDCR	TPS79912DDCT	TPS799315DDCR	TLV9352IDDFR
TLV70030DDCT	TPS79913DDCR	TPS799315DDCT	
TLV70032DDCR	TPS79913DDCT	TPS79933DDCR	

### Group 2 Product Affected:

SN1804026DDFR	TPS562219ADDFR	TPS563210DDFR	TPS565201DDCR
THVD8000DDFR	TPS562219ADDFT	TPS563219ADDFR	TPS565201DDCT
THVD8010DDFR	TPS562219DDFR	TPS563219DDFR	TPS565208DDCR
TPS562210ADDFR	TPS563210ADDFR	SN1706035DDCR	TPS565208DDCT
TPS562210DDFR	TPS563210ADDFT	SN1706035DDCT	

## Qualification Report (SOT-23-THN)

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	PHI TPS563249DDC	CDAT TPS563249DDC
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/T HB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHA ST/ AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS563201DDC)	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	JCETC8 TPS563208DDC	JCETJY TLV62569PDDC
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/T HB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0

	Stress Test	Duration	JCETC8 TPS563208DDC	JCETJY TLV62569PDDC
UHA ST/ AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (TPS27081ADDC)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	UTL LM73CxQDDCRQ1	TIEM TPL5010QDDCRQ1	HNA LV2862XLV DDC
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0	3/231/0
HAST/T HB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0 (a)	3/231/0	3/135/0 (b)
UHA ST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	2/44/0 (TPS62242QDDC)	2/44/0 (LM2734XQMK)	3/66/0 (b)
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a – Data collected on TPS3702E X33QDDCRQ1 and LM73CxQDDCRQ1

Note b – Data collected on LMP8640QMKX-T/NOPB

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
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